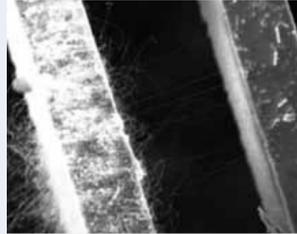
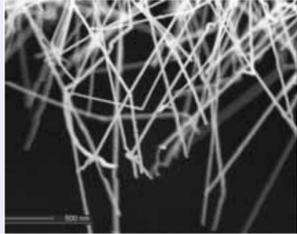


Micro Electromechanical Systems Division (MEMS)

Serving Engineers Around the World in the Micro Electromechanical Systems Areas

Mission Statement

- Foster and lead the promotion of miniature devices combining electrical, mechanical, optical, chemical and/or biological components fabricated via integrated circuit or other similar manufacturing techniques

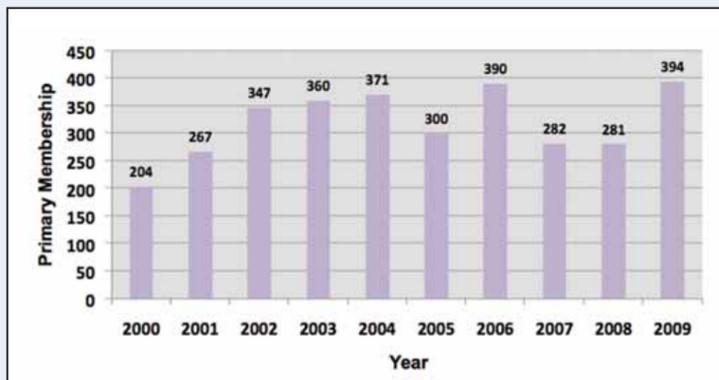


MEMS Division Goals

- Facilitate interaction and discussion among the MEMS community and generate opportunities for collaboration to spawn creativity.
- Identify the needs and problems of the MEMS community and bring together appropriate people to address them.
- Provide a platform to generate standards and guidelines for MEMS processes and technologies.
- Educate and inform engineers and scientists in various fields of the ongoing developments in the MEMS field.
- Train new multi-disciplinary MEMS researchers for furthering the field.

Division's Health

- Fast growth path in the first five year
- Division stability maintained afterwards
- Competition from the ASME Nanotechnology Institute since 2002
- 2009 is a record year!



Division History

- 15 consecutive MEMS Symposia were held during the ASME Winter Annual Meetings or International Mechanical Engineering Congress and Expositions since 1990
- Was been a technical panel under the Dynamic Systems and Controls Division before 1998
- MEMS subdivision was established in 1998 based on ASME by-law B5.8.5.
- MEMS division was established in 2004 based on ASME by-law B5.8.6.

Division Major Activities

- IMECE:** MEMS is a multi-disciplinary field and the division has been working with other ASME divisions, including Dynamic Systems and Controls, Heat Transfer, Fluids Engineering, Applied Mechanics, Bioengineering, Design Engineering, Electronic and Photonic Packaging, Manufacturing Engineering, etc.
- InterPacK 2011:** July 6–8, 2011 Portland, Oregon
EPPD continues to be the primary sponsor of InterPACK, with co-sponsorship from the MEMS Division, the Nanotechnology Institute, and the Heat Transfer Division.

Growth Potential



Name	Sponsor	Frequency	Attendance
International Conference on Solid-State Sensors and Actuators	IEEE	Every two years	>1000
International Micro Electro Mechanical Systems Conference	IEEE	Every year	>500
Solid-State Sensors and Actuators Workshop	Transducers Foundation	Every two years	>500
Micromachining and Microfabrication	SPIE	Every year	>300

ASME 3rd International Conference on Micro- and Nanosystems

- <http://www.asmeconferences.org/IDETC09/index.cfm>
- Deadlines:** Submission of Abstract/Draft Paper: February 27, 2009
Author Notification of Acceptance: April 13, 2009
Submission of Final Paper: May 15, 2009

Symposium Organizers:

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Division Journal

- IEEE/ASME Journal of Microelectromechanical Systems is ranked No. 7 out of all IEEE journals in terms of impact factor



Executive Committee

Position	Name	Affiliation
Chair	Cetin Cetinkaya	Clarkson University
Vice Chair	Aman Haque	Penn-State University
Secretary/Treasurer	Channy Wong	Sandia National Labs
Program and Editorial Committee Chair	E.-H. Yang	Stevens Institute
Past Chair	Kim Turner	UC-Santa Barbara